



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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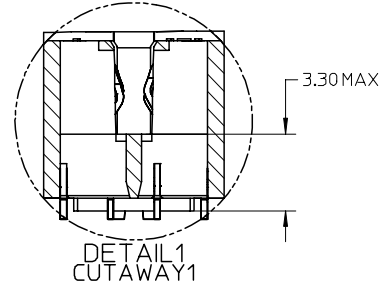
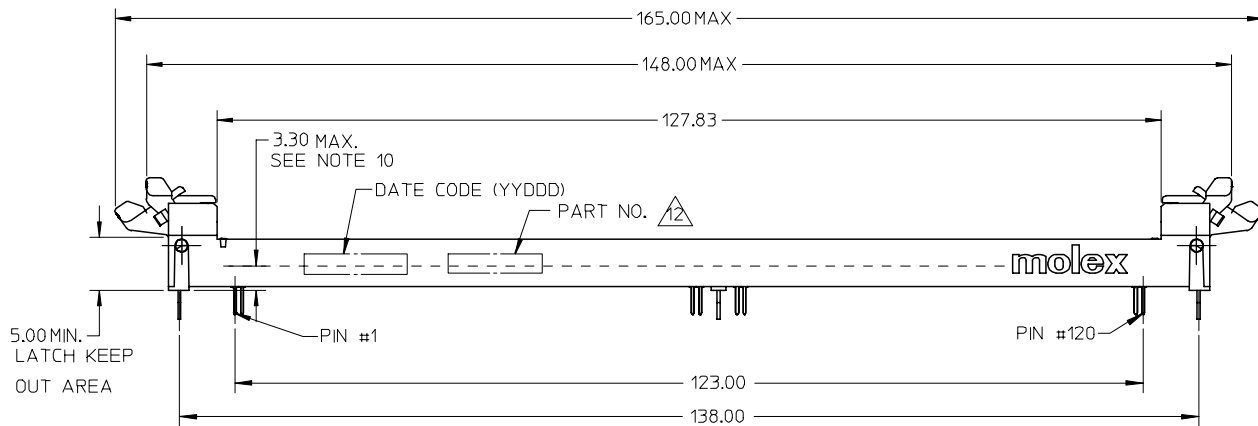
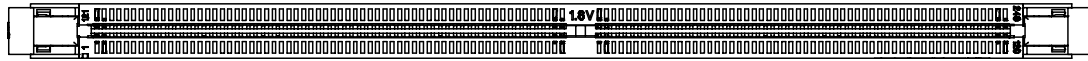
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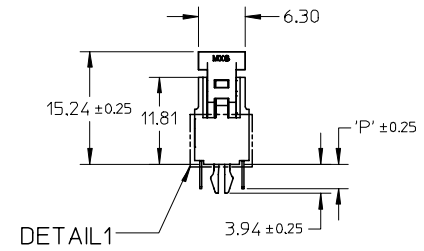
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NOTES:

1. MATERIALS  
HOUSING - HIGH TEMP. NYLON GLASS FILLED, UL 94 V-0, BLACK.  
EJECTOR - HIGH TEMP. NYLON GLASS FILLED, UL 94 V-0, BLACK.  
TERMINAL - COPPER ALLOY
2. PLATING - SEE TABLE IN SHEET 5.
3. CARD SLOT ACCEPTS 1.27±0.10 MM MODULE THICKNESS.  
(MEASURED OVER P.C. PADS)
4. RECOMMENDED MODULE LAYOUT SHALL BE AS PER JEDEC MO-237.
5. REFER TO PRODUCT SPEC, PS-87978-013 FOR PERFORMANCE SPECIFICATIONS.
6. PRODUCT SHALL BE PACKED IN TRAY.
7. PRODUCT SHALL HAVE DATE CODE STAMPED ON SIDE OF HOUSING.
8. KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR IS MOUNTED ONTO THE PCB WHICH DOES NOT INCLUDE THE LATCH.
9. REFER TO CRITICAL JEDEC INFORMATION FOR SOCKET OUTLINE PER SO-001.
10. DIMM MODULE SEATING PLANE FROM TOP OF PCB.
11. CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.
12. PART NUMBER SHALL BE MARKED LEGIBLY AS 87978-\*\*\*\*



REVISED EC NO: S2008-0235 DRWN:CMTEO 2007/09/27 CHKD:CCTEH 2007/09/27 APPR:SHLENI 2007/09/28	DESCRIPTION QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
				MM ONLY	NTS	METRIC		
				DRAWN BY	DATE	TITLE		
				CCTEH	2005/01/03	DDR2 DIMM, 1MM PITCH		
		3 PLACES ± --- ± ---		CHECKED BY	DATE	240 CKTS, FORK-LOCK VERS		
		2 PLACES ± 0.20 ± ---		SRRAMESH	2005/08/30	VLP LATCH		
		1 PLACE ± --- ± ---		APPROVED BY	DATE	MOLEX MOLEX INCORPORATED		
		ANGULAR ± 5 °		GGLEE	2005/08/30	SD-87978-001		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.	DOCUMENT NO.	SHEET NO.		
				SEE TABLE		1 OF 5		
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

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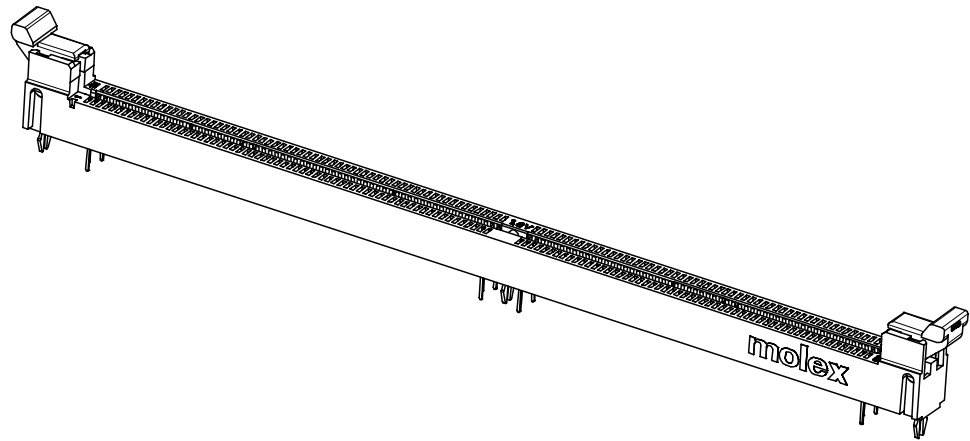
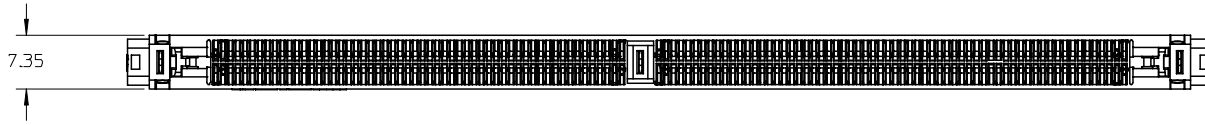
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REVISED EC NO: S2008-0235 DRWN:CMTEO 2007/09/27 CHKD:CCTEH 2007/09/27 APPR:SHLENI 2007/09/28	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± ---	mm INCH	DRAWN BY CCTEH	DATE 2005/01/03	TITLE DDR2 DIMM, 1MM PITCH 240 CKTS, FORK-LOCK VERS VLP LATCH					
		3 PLACES ± --- ± ---	2 PLACES ± 0.20 ± ---	CHECKED BY SRRAMESH	DATE 2005/08/30						
		1 PLACE ± --- ± ---	ANGULAR ± 5 °	APPROVED BY GGLEE	DATE 2005/08/30	MOLEX INCORPORATED					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE TABLE		MATERIAL NO. DOCUMENT NO. SD-87978-001				SHEET NO. 2 OF 5		

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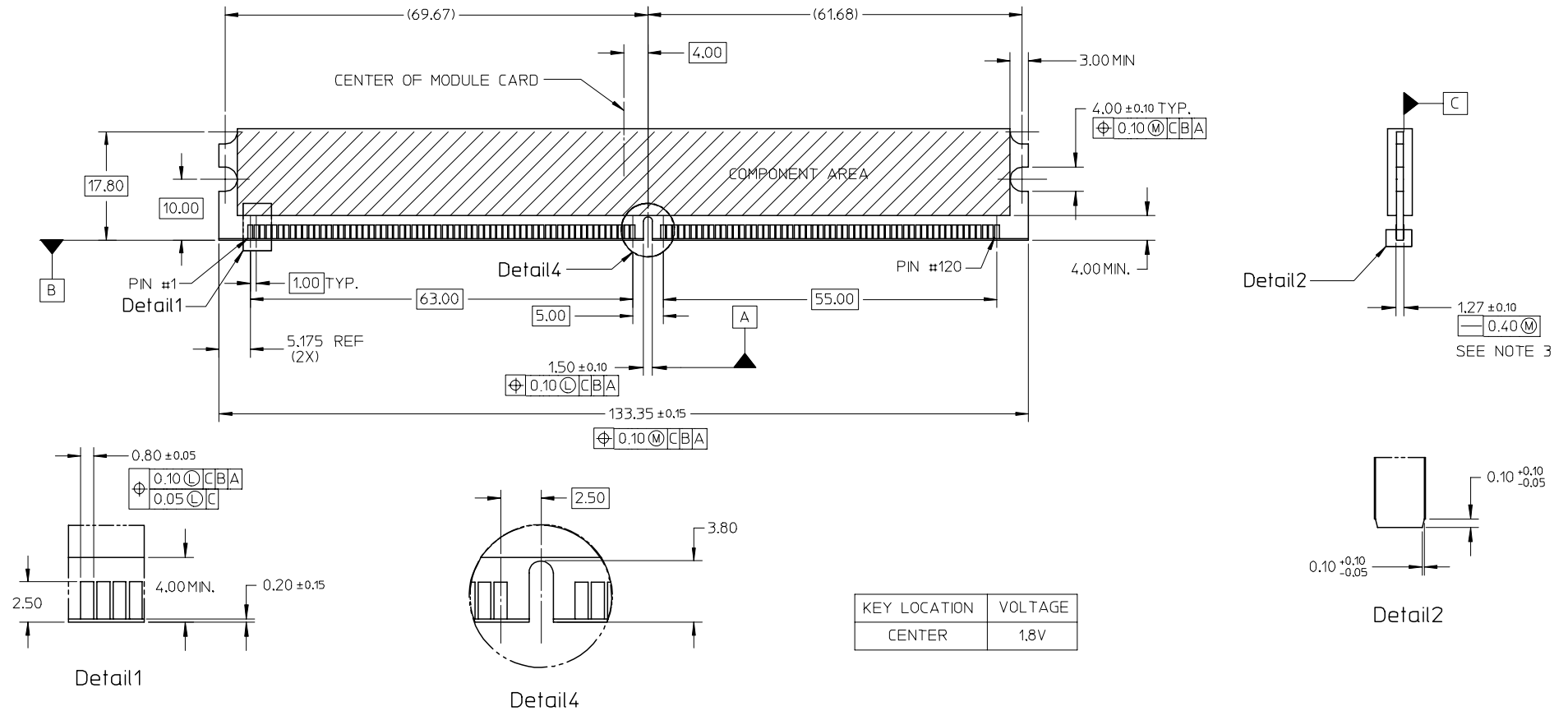
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RECOMMENDED MODULE LAYOUT



NOTES:  
1. MODULE CARD USED FOR TESTS ARE WITH 0.10MM CHAMFER.

REVISED	DESCRIPTION
EC NO: S2008-0235	2007/09/27
DRWN:CMTEO	2007/09/27
CHKD:CCTEH	2007/09/28
APPR:SHLENI	2007/09/28

QUALITY SYMBOLS	▽=0
	∇=0

GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE
	MM ONLY
	SCALE NTS
	DESIGN UNITS METRIC
	THIRD ANGLE PROJECTION
4 PLACES ± --- ± ---	DRAWN BY DATE
3 PLACES ± --- ± ---	CCTEH 2005/01/03
2 PLACES ± 0.20 ± ---	CHECKED BY DATE
1 PLACE ± --- ± ---	SRRAMESH 2005/08/30
ANGULAR ± 5 °	APPROVED BY DATE
	GGLEE 2005/08/30
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO.
	SEE TABLE
	SIZE A3

TITLE	SDR2 DIMM, 1MM PITCH
	240 CKTS, FORK-LOCK VERS
	VLP LATCH
	MOLEX INCORPORATED
DOCUMENT NO.	SD-87978-001
SHEET NO.	3 OF 5

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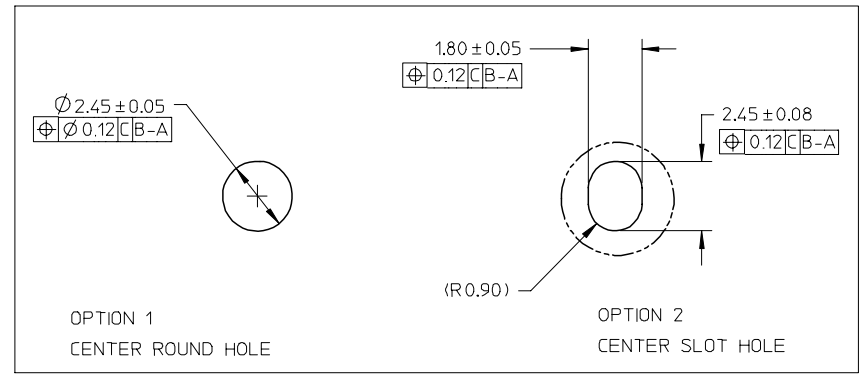
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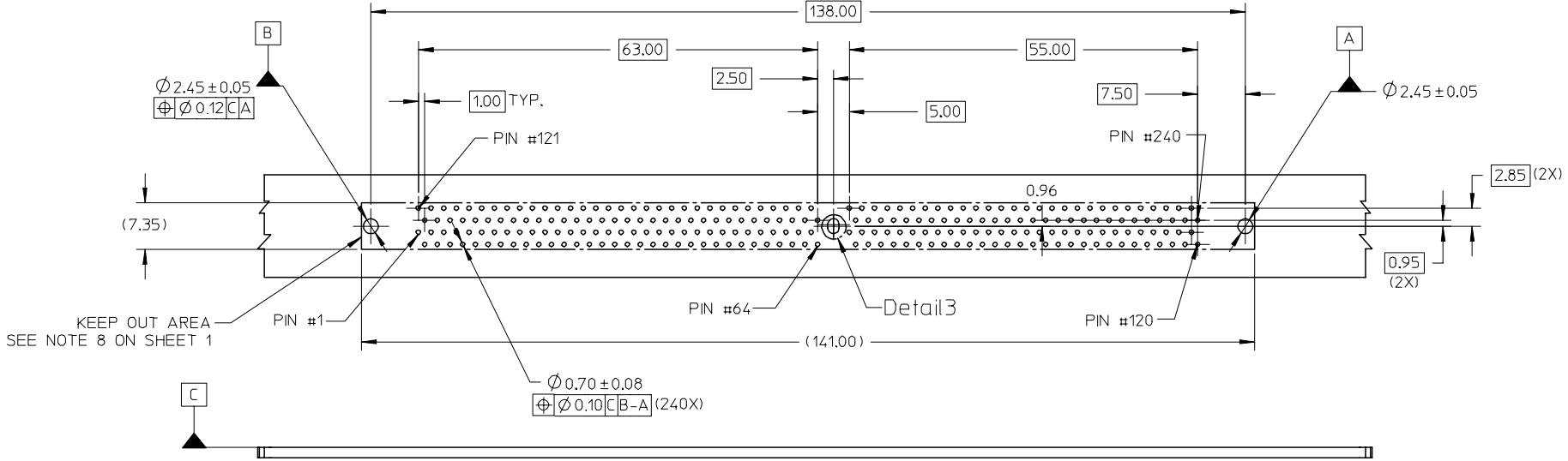
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(SEE RECOMMENDED THICKNESS IN TABLE)  
RECOMMENDED PCB LAYOUT  
CONNECTOR SIDE

Detail3



KEEP OUT AREA  
SEE NOTE 8 ON SHEET 1

REVISED EC NO: S2008-0235 DRWN:CMTEO 2007/09/27 CHKD:CCTEH 2007/09/27 APPR:SHLENI 2007/09/28	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± 0.20 ± ---	1 PLACE ± --- ± ---	ANGULAR ± 5 °	DRAWN BY CCTEH	DATE 2005/01/03	TITLE DDR2 DIMM, 1MM PITCH 240 CKTS, FORK-LOCK VERS VLP LATCH		
							CHECKED BY SRRAMESH	DATE 2005/08/30	MOLEX INCORPORATED		
							APPROVED BY GGLEE	DATE 2005/08/30	DOCUMENT NO. SD-87978-001		
B	REV	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SHEET NO. 4 OF 5		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

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PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	LATCH COLOR
87978-0021	CENTER (1.8V)	2.67	1.57	0.38µM / 15 µIN MIN. GOLD ON CONTACT, 2.54µM/ 100µIN MIN. TIN ON SOLDERTAILS, 1.27µM/ 50µIN MIN. NICKEL UNDERPLATE	BLACK
87978-1021	CENTER (1.8V)	3.18	2.36		
87978-0031	CENTER (1.8V)	2.67	1.57	0.03µM / 1 µIN MIN. GOLD ON CONTACT, 2.54µM/ 100µIN MIN. TIN ON SOLDERTAILS, 1.27µM/ 50µIN MIN. NICKEL UNDERPLATE	
87978-1031	CENTER (1.8V)	3.18	2.36		
87978-0051	CENTER (1.8V)	2.67	1.57	0.76µM / 30 µIN MIN. GOLD ON CONTACT, 2.54µM/ 100µIN MIN. TIN ON SOLDERTAILS, 1.27µM/ 50µIN MIN. NICKEL UNDERPLATE	
87978-1051	CENTER (1.8V)	3.18	2.36		

<b>REVISED</b> EC NO: S2008-0235 DRWN:CMTEO 2007/09/27 CHKD:CCTEH 2007/09/27 APPR:SHLENI 2007/09/28	QUALITY SYMBOLS =0 =0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± ---	DRAWN BY CCTEH	DATE 2005/01/03	TITLE DDR2 DIMM, 1MM PITCH 240 CKTS, FORK-LOCK VERS VLP LATCH				
		3 PLACES ± --- ± ---	CHECKED BY SRRAMESH	DATE 2005/08/30					
		2 PLACES ± 0.20 ± ---	APPROVED BY GGLEE	DATE 2005/08/30	MATERIAL NO. SEE TABLE			DOCUMENT NO. SD-87978-001	
1 PLACE ± --- ± ---	ANGULAR ± 5 °								
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

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